Electronic Version
Stylesheet Version v1.1.1

Claims

[c1] A water soluble protective paste for protecting metal circuits during the manufacture of electronic modules comprising a salt, a glycerol and a densifier dissolved in water.

[c2] The water soluble protective paste of claim 1 wherein the salt is 5% to 110% of the glycerol in weight and the densifier is 5% to 90% of the salt in weight.

[c3] The water soluble protective paste of claim 2 wherein the salt is 8% to 30% of the glycerol in weight and the densifier is 7% to 25% of the salt in weight.

[c4] The water soluble protective paste of claim 1 wherein the salt is Sodium citrate.

[c5] The water soluble protective paste of claim 1, wherein the salt is Potassium citrate.

[c6] The water soluble protective paste of claim 1 wherein the salt is about 25% of the glycerol in weight.

[c7] The water soluble protective paste of claim 6 wherein the densifier is about 20% of the salt in weight.

[c8] The water soluble protective paste of claim 1 wherein the densifier is a Hydrocolloid.

[c9] The water soluble protective paste of claim 8 wherein the Hydrocolloid is Gum Acacia.

[c10] A method of selectively dispensing the water soluble protective paste of claim 1 by means of offset printing.

[c11] A method of protecting metal circuits and pads on the surface of an electronic board during manufacturing steps, comprising:
- selectively dispensing over the metal circuits and pads the water soluble protective paste of any claim 1 to 9, by means of offset printing;
- drying the dispensed layer obtaining a solid protective film.

[c12] A method for manufacturing a multi chip module having on the same substrate at least one wire bonded chip and at least one Surface Mount Technology (SMT) chip, the method comprising the steps of:
- protecting, with the method of claim 11, the metal circuits and pads to which the wire bonded chip will be connected;
- mounting the at least one SMT chip;
- removing the protective layer from the metal circuits

and pads;

- attaching and bonding the at least one Wire Bond chip.